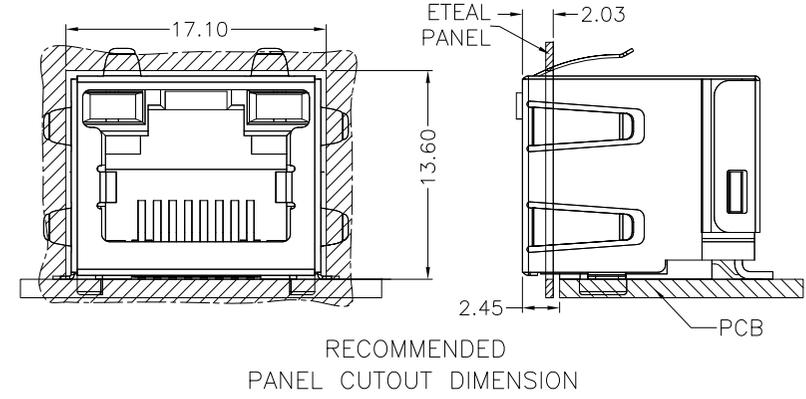
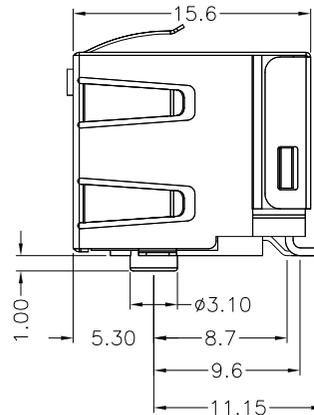
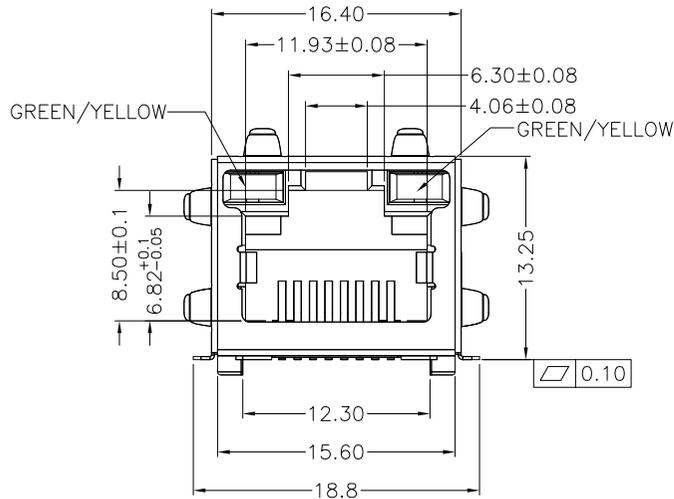
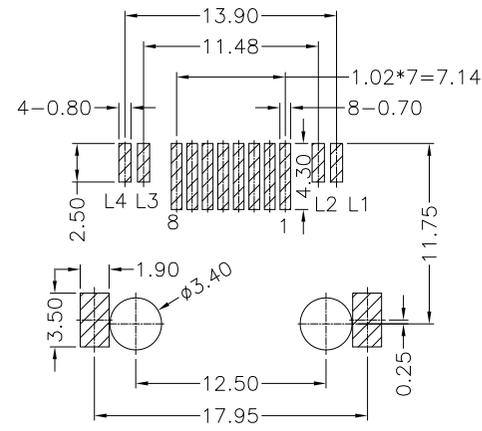
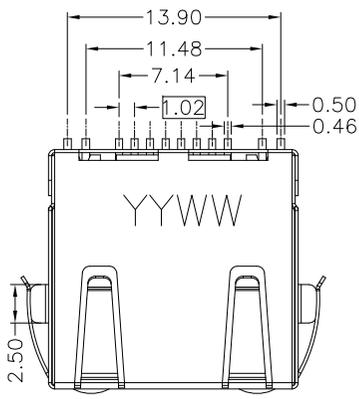


# GP Component

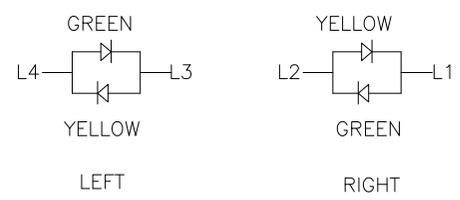
REV.	ECN NO.	LOCATIONS	DESCRIPTION	DATE	DESIGN
AO			Initial	2016/01/07	Phebe Su



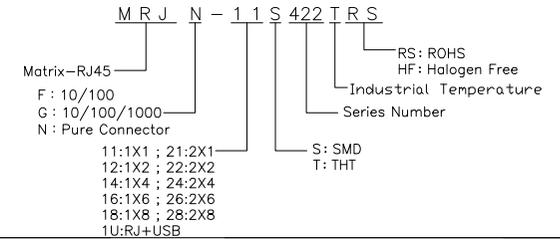
- NOTES:
- MATERIALS:  
 HOUSING: HIGH TEMP. THERMOPLASTIC, LCP, UL 94V-0, BLACK.  
 CONTACTS: T=0.30 mm PHOSPHOR BRONZE, 50u" NICKEL UNDERPLATE ON ALL AREA, 100u" MATTE TIN ON SOLDER TAIL, 6u" GOLD ON CONTACT AREA.  
 SHELL: BRASS, T=0.20mm
  - OPERATING TEMPERATURE: -40°C ~ +85°C
  - LED SPEC:  
 FORWARD VOLTAGE: 1.8~2.4V  
 REVERSE CURRENT: 5uA MAX  
 PEAK WAVE LENGTH  
 GREEN: 565~575nm  
 YELLOW: 585~590nm
  - JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUBPART F



RECOMMENED PCB LAYOUT (COMPONENT SIDE)  
 TOLERANCE ±0.05



### ORDER INFORMATION :



NO	VARIETY	QTY	MATERIAL	REMARK
	Matrix Electronics Co.,Ltd			
TOLERANCE: X.X ±0.38 X.XX ±0.25 X.XXX ±0.13 ANGLE: ±3°		DESIGN BY : Phebe Su	DATE : 2016/01/07	PART NAME: RJ45 1X1 PCB JACK WITH LED SMT TYPE
APPROVED BY1: Richard Hsieh		DATE : 2016/01/07	PART NO.	MRJN-11S422TRS
APPROVED BY2: Richard Hsieh		DATE : 2016/01/07	MOLD NO.	NA
UNIT: mm [inch]		DATE :	DRAW NO.	
SCALE:1:1	SIZE:A4	DATE : 2016/01/07	SHEET NO.	1 OF 1